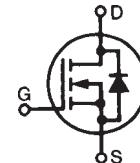


**X2-Class HiPerFET™
Power MOSFET**
IXFA34N65X2

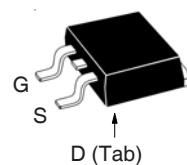
V_{DSS} = 650V
 I_{D25} = 34A
 $R_{DS(on)}$ ≤ 100mΩ



N-Channel Enhancement Mode
Avalanche Rated

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	$T_J = 25^\circ\text{C}$ to 150°C	650	V
V_{DGR}	$T_J = 25^\circ\text{C}$ to 150°C , $R_{GS} = 1\text{M}\Omega$	650	V
V_{GSS}	Continuous	±30	V
V_{GSM}	Transient	±40	V
I_{D25}	$T_C = 25^\circ\text{C}$	34	A
I_{DM}	$T_C = 25^\circ\text{C}$, Pulse Width Limited by T_{JM}	68	A
I_A	$T_C = 25^\circ\text{C}$	10	A
E_{AS}	$T_C = 25^\circ\text{C}$	1	J
dv/dt	$I_S \leq I_{DM}$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ\text{C}$	50	V/ns
P_D	$T_C = 25^\circ\text{C}$	540	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	Maximum Lead Temperature for Soldering	300	°C
dT/dt	Heating / Cooling rate, 175°C - 210°C	50	°C/min
T_{SOLD}	1.6 mm (0.062in.) from Case for 10s	260	°C
F_c	Mounting Force	10..65 / 2.2..14.6	N/lb
Weight		2.5	g

TO-263



G = Gate D = Drain
S = Source Tab = Drain

Features

- International Standard Package
- Low $R_{DS(ON)}$ and Q_G
- Avalanche Rated
- Low Package Inductance

Advantages

- High Power Density
- Easy to Mount
- Space Savings

Applications

- Switch-Mode and Resonant-Mode Power Supplies
- DC-DC Converters
- PFC Circuits
- AC and DC Motor Drives
- Robotics and Servo Controls

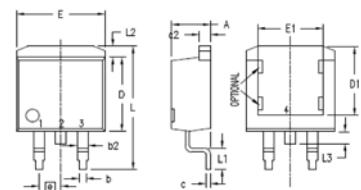
Symbol Test Conditions
($T_J = 25^\circ\text{C}$, Unless Otherwise Specified)

Characteristic Values
Min. Typ. Max.

BV_{DSS}	$V_{GS} = 0\text{V}$, $I_D = 1\text{mA}$	650		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 2.5\text{mA}$	3.5	5.0	V
I_{GSS}	$V_{GS} = \pm 30\text{V}$, $V_{DS} = 0\text{V}$		±100	nA
I_{DSS}	$V_{DS} = V_{DSS}$, $V_{GS} = 0\text{V}$ $T_J = 125^\circ\text{C}$		10	μA
$R_{DS(on)}$	$V_{GS} = 10\text{V}$, $I_D = 0.5 \cdot I_{D25}$, Note 1		1.75	mA
			100	mΩ

Symbol (T _j = 25°C, Unless Otherwise Specified)	Test Conditions	Characteristic Values		
		Min.	Typ.	Max
g_{fs}	V _{DS} = 10V, I _D = 0.5 • I _{D25} , Note 1	12	20	S
R_{Gi}	Gate Input Resistance	0.8		Ω
C_{iss} C_{oss} C_{rss}	V _{GS} = 0V, V _{DS} = 25V, f = 1MHz	3230 2000 2		pF pF pF
Effective Output Capacitance				
C_{o(er)} C_{o(tr)}	Energy related Time related	V _{GS} = 0V V _{DS} = 0.8 • V _{DSS}	130 486	pF pF
t_{d(on)} t_r t_{d(off)} t_f	Resistive Switching Times V _{GS} = 10V, V _{DS} = 0.5 • V _{DSS} , I _D = 0.5 • I _{D25} R _G = 10Ω (External)	37 60 64 30		ns ns ns ns
Q_{g(on)} Q_{gs} Q_{gd}	V _{GS} = 10V, V _{DS} = 0.5 • V _{DSS} , I _D = 0.5 • I _{D25}	56 19 18		nC nC nC
R_{thJC}			0.23	°C/W

TO-263 (IXFA) Outline

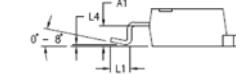


1 = Gate

2 = Drain

3 = Source

4 = Drain



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.160	.190	4.06	4.83
A1	.080	.110	2.03	2.79
b	.020	.039	.51	.99
b2	.045	.055	1.14	1.40
c	.016	.029	.40	.74
c2	.045	.055	1.14	1.40
D	.340	.380	8.64	9.65
D1	.315	.350	8.00	8.89
E	.380	.410	9.65	10.41
E1	.245	.320	6.22	8.13
e	.100	BSC	2.54	BSC
L	.575	.625	14.61	15.88
L1	.090	.110	2.29	2.79
L2	.040	.055	1.02	1.40
L3	.050	.070	1.27	1.78
L4	0	.005	0	.013

Source-Drain Diode

Symbol	Test Conditions (T _J = 25°C, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max
I _s	V _{GS} = 0V			34 A
I _{SM}	Repetitive, pulse Width Limited by T _{JM}			136 A
V _{SD}	I _F = I _s , V _{GS} = 0V, Note 1			1.4 V
t _{rr} Q _{RM} I _{RM}	I _F = 17A, -di/dt = 100A/μs V _R = 100V	164 1.2 14.4		ns μC A

Notes: 1. Pulse test, $t \leq 300\mu s$, duty cycle, $d \leq 2\%$.

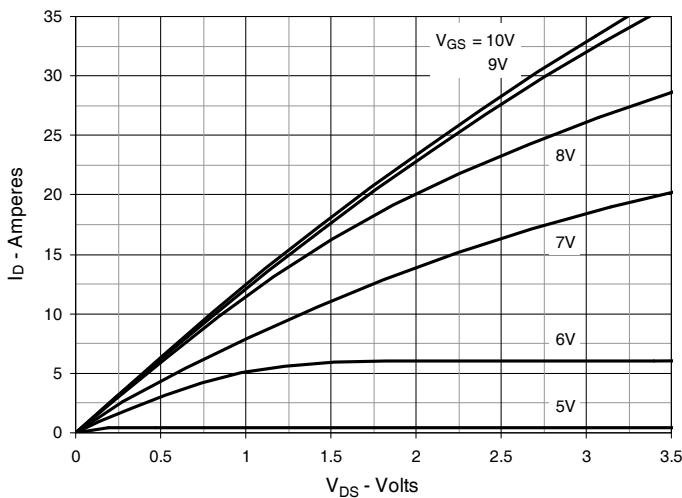
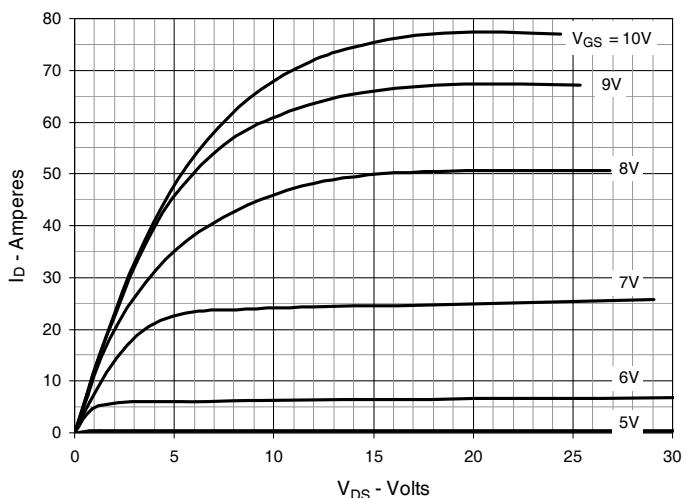
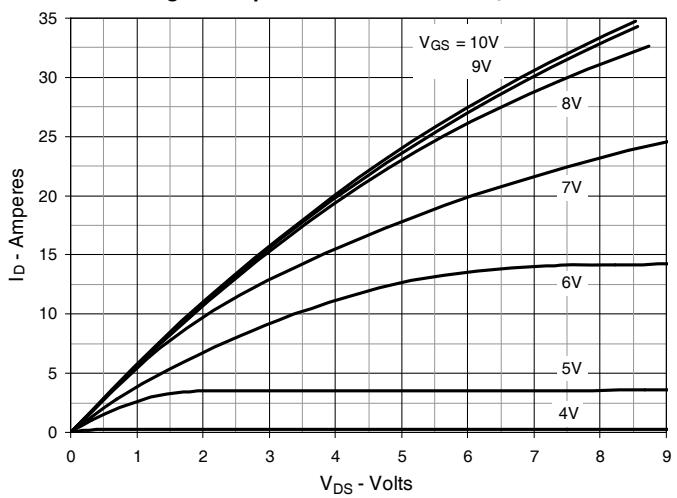
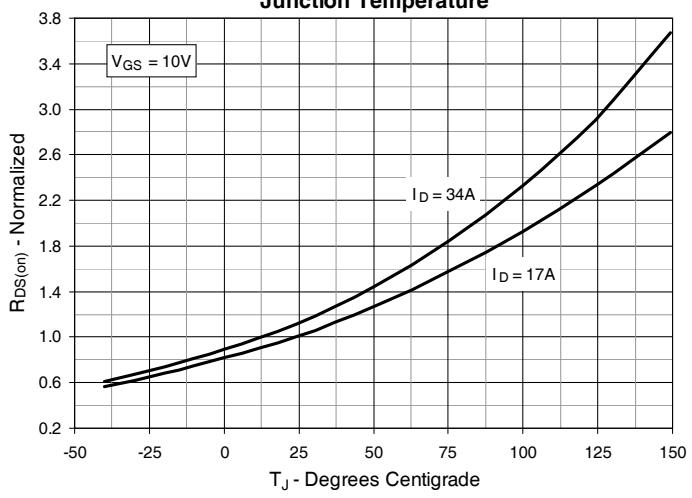
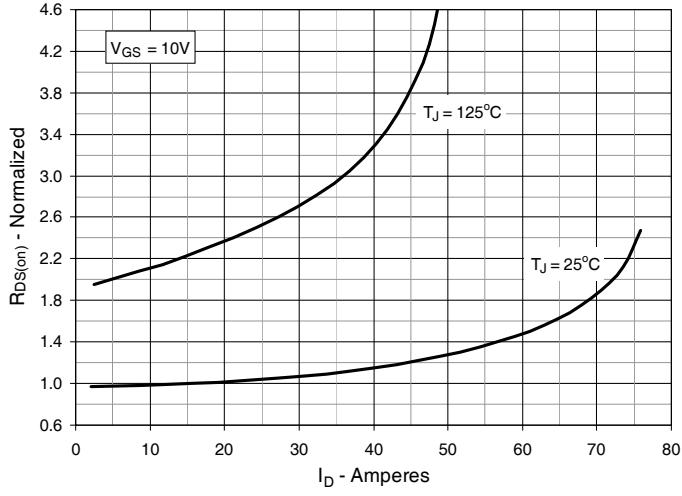
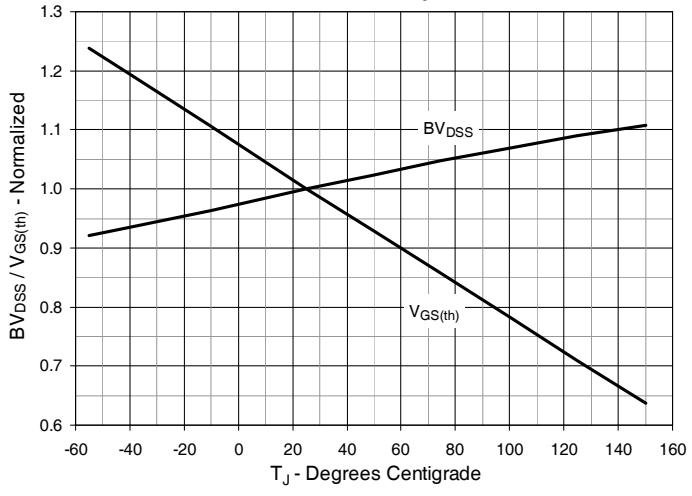
Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$ **Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$** **Fig. 3. Output Characteristics @ $T_J = 125^\circ\text{C}$** **Fig. 4. $R_{DS(on)}$ Normalized to $I_D = 17\text{A}$ Value vs. Junction Temperature****Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 17\text{A}$ Value vs. Drain Current****Fig. 6. Normalized Breakdown & Threshold Voltages vs. Junction Temperature**

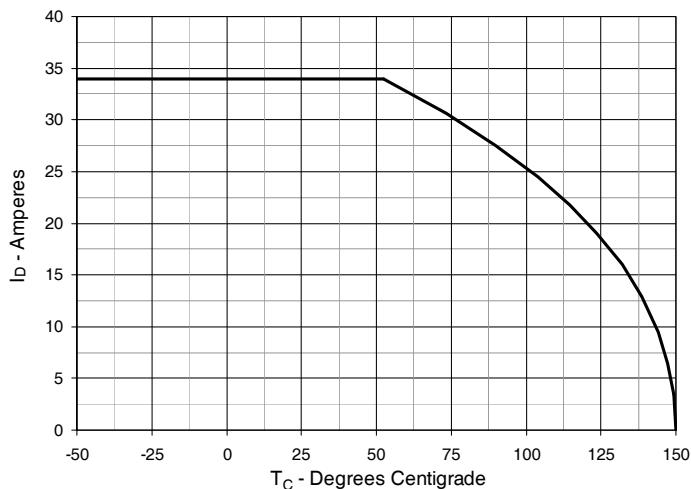
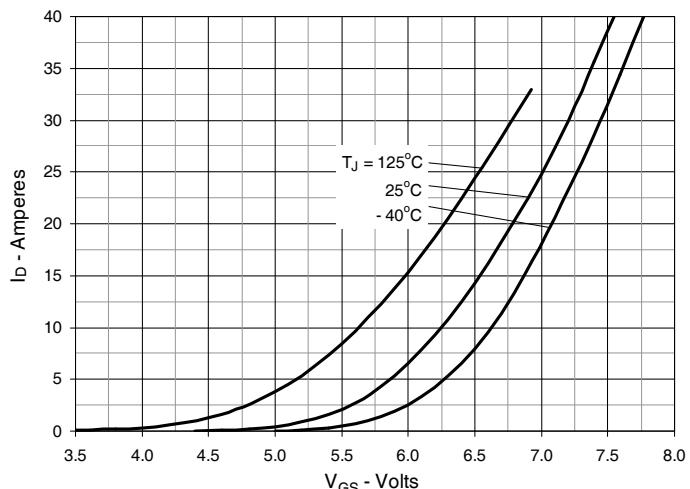
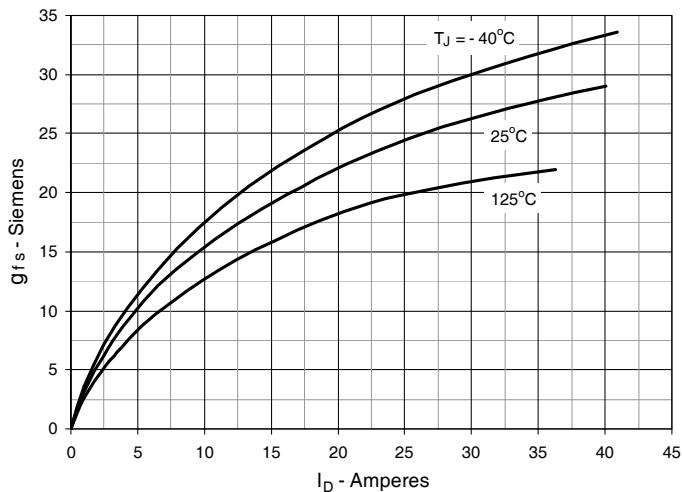
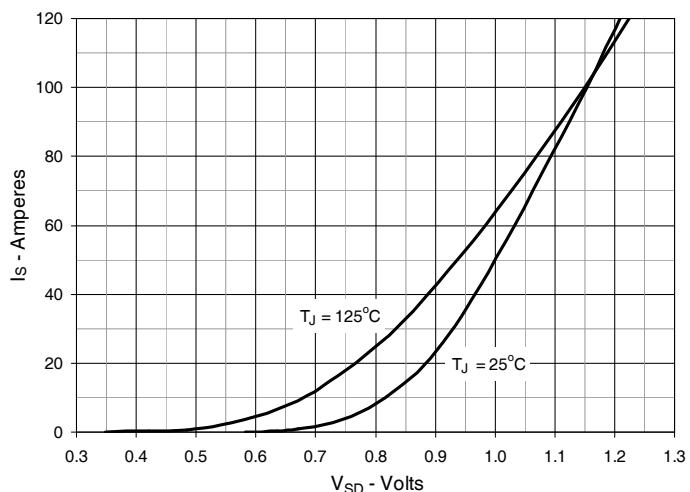
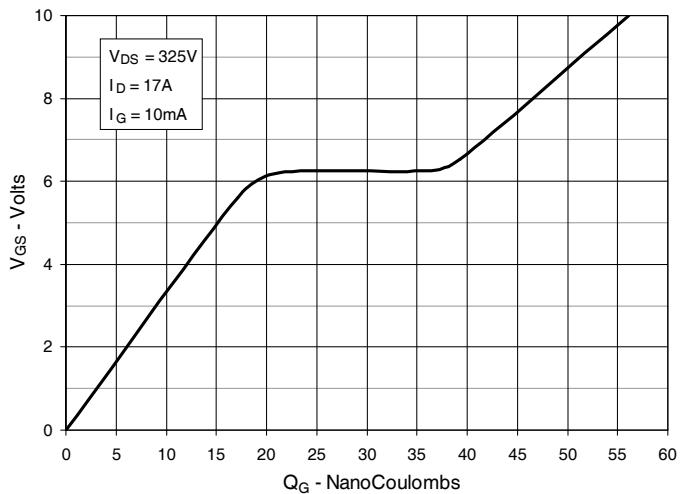
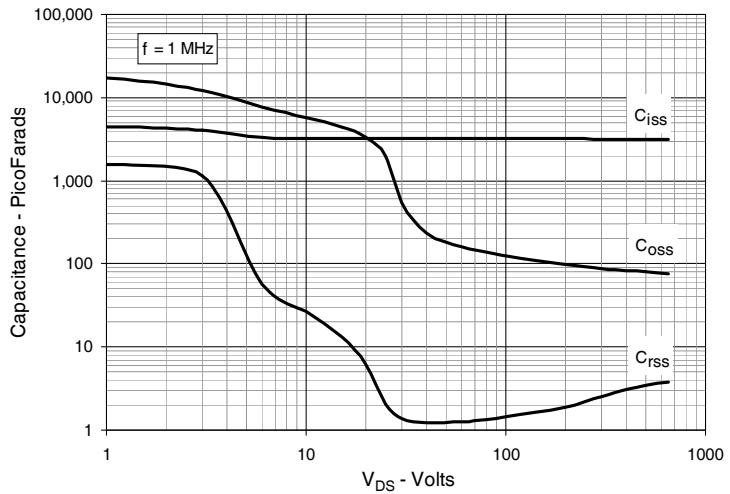
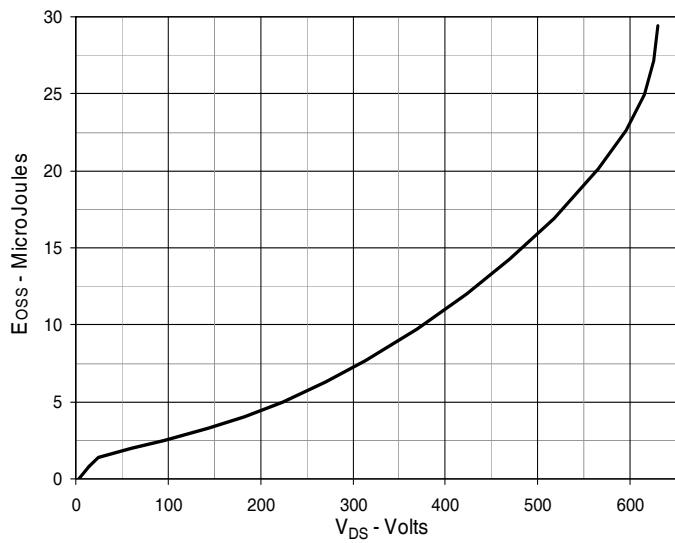
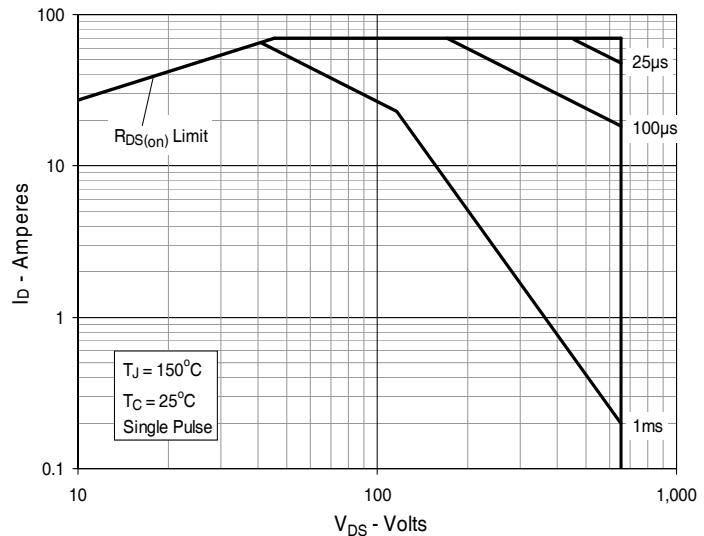
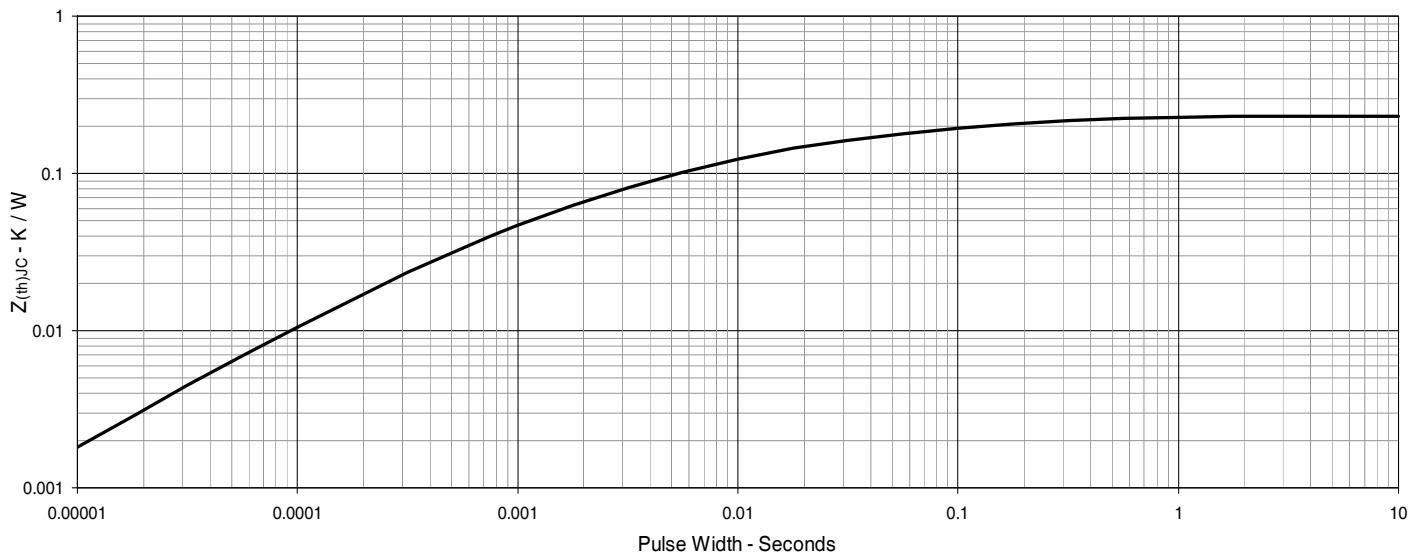
Fig. 7. Maximum Drain Current vs. Case Temperature**Fig. 8. Input Admittance****Fig. 9. Transconductance****Fig. 10. Forward Voltage Drop of Intrinsic Diode****Fig. 11. Gate Charge****Fig. 12. Capacitance**

Fig. 13. Output Capacitance Stored Energy**Fig. 14. Forward-Bias Safe Operating Area****Fig. 15. Maximum Transient Thermal Impedance**



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